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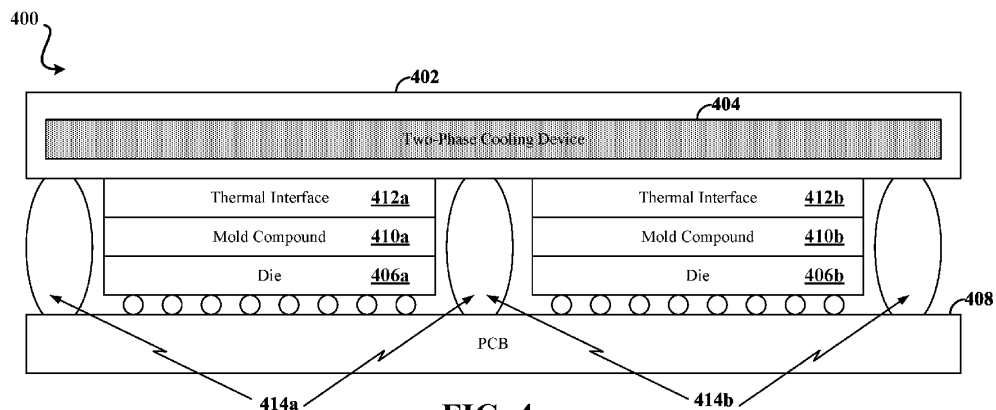


FIG. 4

(57) Abstract: Aspects of the disclosure relate to thermal management of devices, such as mobile devices configured for wireless communication in wireless communication networks. A device includes a plurality of electronic components. An electromagnetic interference (EMI) shield is disposed on the electronic components, and a plurality of EMI gaskets are disposed between the electronic components. Each of the EMI gaskets surrounds a respective one of the plurality of electronic components. An evaporative cooler device embedded within the EMI shield is configured to transfer heat away from at least a portion of the electronic components.

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